

PHYSICAL CONFIGURATION



HTR TYPE	POWER RATING at 25°C		DIMENSIONS (mm	ı)	RESISTANCE		TYPICAL WT.
		L <u>+</u> 1.0	D*	P <u>+</u> 1.0	min	max	[gms]
H-1M	1W	6.5	3.7(<u>+</u> 0.3)	-	R01	1K5	0.5
H-2M	2W	9.0	3.7(<u>+</u> 0.3)	-	R01	2K7	0.6
H-3AS	3W	13.0	5.5(<u>+</u> 0.5)	18.0	R01	10K	1.2
H-5S	5W	19.5	6.5(<u>+</u> 0.5)	24.5	R01	16K	2.0

 D^* for non-inductive types & for resistance values < 1R0 + 0.8mm allowed.

4.0 <u>+</u> 0.3

MOUNTING SPECIFICATIONS

For the guidance of the Design Engineer our applications laboratory has given the recommended pad size and geometry which is shown below :-









SIDE VIEW



HTR TYPE	POWER RATING	DIMENSIONS (mm)						RESISTANCE RANGE		TYPICAL WT. PER PC
	at 25°C	A [MAX]	B [<u>+</u> 1.0]	C [MAX]	D[<u>+</u> 0.05]	E [<u>+</u> 0.5]	Z [<u>+</u> 1.0]	min	max	[gms]
2WS	2W	12.0	17.0	4.8	0.8	5.0	6.5	R10	5K6	0.95
2WSA	2W	9.0	13.4	4.5	0.8	4.5	6.5	R05	2K2	
3WS	3W	14.5	18.7	6.0	0.8	6.5	8.0	R01	10k	
4WS	4W	15.5	20.0	6.0	0.8	8.0	8.0	R10	12K	1.25
5WS	5W	16.5	18.7	7.0	0.8	6.5	8.0	R01	12k	

MOUNTING / ASSEMBLY DATA

For the guidance of the Design Engineer our applications laboratory has given the recommended pad size and geometry which is shown below :-



	DIMENSIONS (mm)					
HTR TYPE	а	b	l			
2WS	2.5	5.5	14.0			
2WSA	2.5 (min)	5.5 (min)	10.0 (max)			
3WS	2.5 (min)	8.0 (min)	15.0 (max)			
4WS	2.5	9.5	17.0			
5WS	2.5 (min)	8.0 (min)	15.0 (max)			



ELECTRICAL AND ENVIRONMENTAL CHARACTERISTICS / DATA

Test	Performance Requirements		
Resistance tolerance	<u>+</u> 10% [K]; <u>+</u> 5% [J]; <u>+</u> 3% [H]; <u>+</u> 2% [G]; <u>+</u> 1% [F]		
Rated ambient temperature	at 25°C full power dissipation derated linearly to zero at 275°C		
Insulation resistance	> 1000 M dry > 100 M wet		
Short time overload	R <u>+</u> [2% + R05]		
Di-electric withstanding voltage	500 Volts r.m.s.		
Ambient operating temperature range	-40°C to + 155°C		
Temperature co-efficient of resistance	<u>+</u> 60ppm/°C to <u>+</u> 400ppm/°C (Depending upon resistance value)		

TYPICAL APPLICATIONS

This series has been evolved in order to fill the gap for melf and surface mount resistors in applications which are too severe for film resistors.

The advantages are superior power to size ratio, higher tolerance to pulse, surge applications & negligible noise.



ORDERING INFORMATION